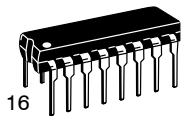


# MECHANICAL CASE OUTLINE

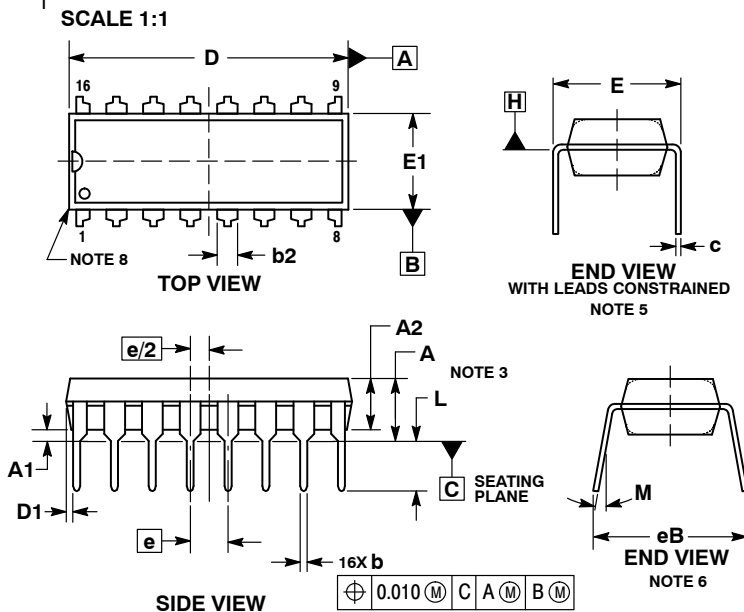
## PACKAGE DIMENSIONS

ON Semiconductor®



### PDIP-16 CASE 648-08 ISSUE V

DATE 22 APR 2015

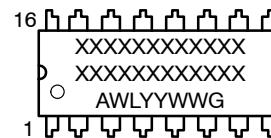


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
4. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
5. DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
6. DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
7. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS).

| DIM | INCHES             |       | MILLIMETERS |       |
|-----|--------------------|-------|-------------|-------|
|     | MIN                | MAX   | MIN         | MAX   |
| A   | ---                | 0.210 | ---         | 5.33  |
| A1  | 0.015              | ---   | 0.38        | ---   |
| A2  | 0.115              | 0.195 | 2.92        | 4.95  |
| b   | 0.014              | 0.022 | 0.35        | 0.56  |
| b2  | 0.060 TYP          |       | 1.52 TYP    |       |
| C   | 0.008              | 0.014 | 0.20        | 0.36  |
| D   | 0.735              | 0.775 | 18.67       | 19.69 |
| D1  | 0.005              | ---   | 0.13        | ---   |
| E   | 0.300              | 0.325 | 7.62        | 8.26  |
| E1  | 0.240              | 0.280 | 6.10        | 7.11  |
| e   | 0.100 BSC 2.54 BSC |       |             |       |
| eB  | ---                | 0.430 | ---         | 10.92 |
| L   | 0.115              | 0.150 | 2.92        | 3.81  |
| M   | ---                | 10°   | ---         | 10°   |

### GENERIC MARKING DIAGRAM\*



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

- |                |                     |
|----------------|---------------------|
| STYLE 1:       | STYLE 2:            |
| PIN 1. CATHODE | PIN 1. COMMON DRAIN |
| 2. CATHODE     | 2. COMMON DRAIN     |
| 3. CATHODE     | 3. COMMON DRAIN     |
| 4. CATHODE     | 4. COMMON DRAIN     |
| 5. CATHODE     | 5. COMMON DRAIN     |
| 6. CATHODE     | 6. COMMON DRAIN     |
| 7. CATHODE     | 7. COMMON DRAIN     |
| 8. CATHODE     | 8. COMMON DRAIN     |
| 9. ANODE       | 9. GATE             |
| 10. ANODE      | 10. SOURCE          |
| 11. ANODE      | 11. GATE            |
| 12. ANODE      | 12. SOURCE          |
| 13. ANODE      | 13. GATE            |
| 14. ANODE      | 14. SOURCE          |
| 15. ANODE      | 15. GATE            |
| 16. ANODE      | 16. SOURCE          |

|                         |                    |  |
|-------------------------|--------------------|--|
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